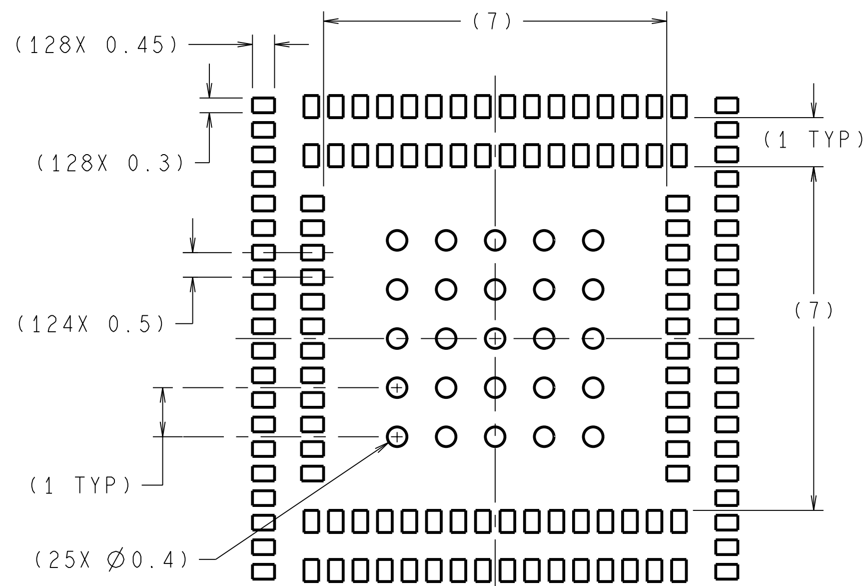
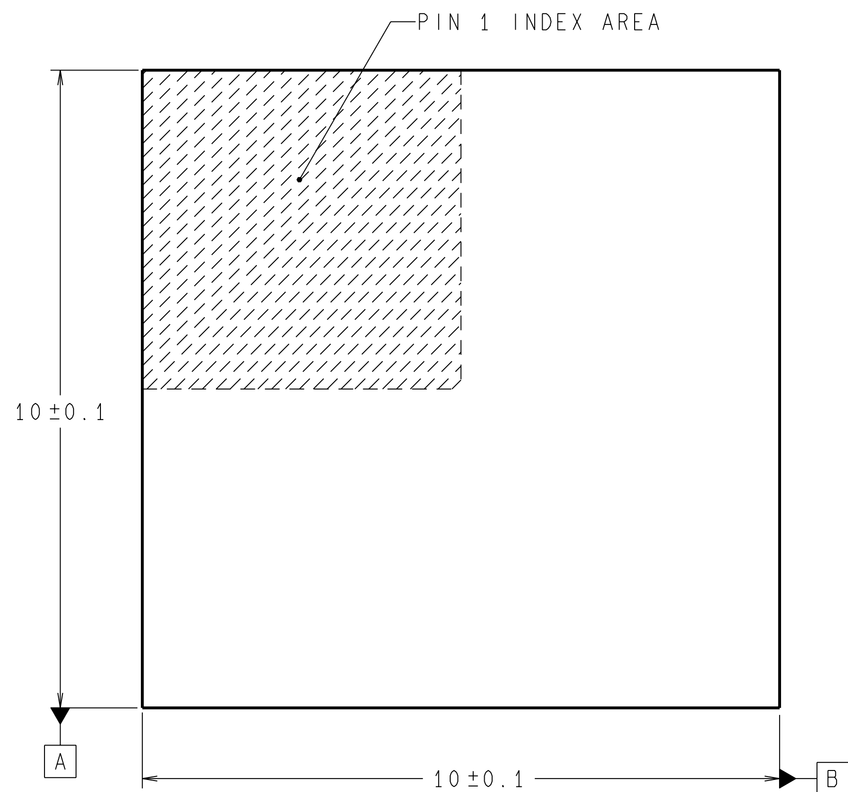
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	211	02/27/2001	TL/GN
B	CORRECT LAND PATTERN	306	05/25/2001	TL/AT

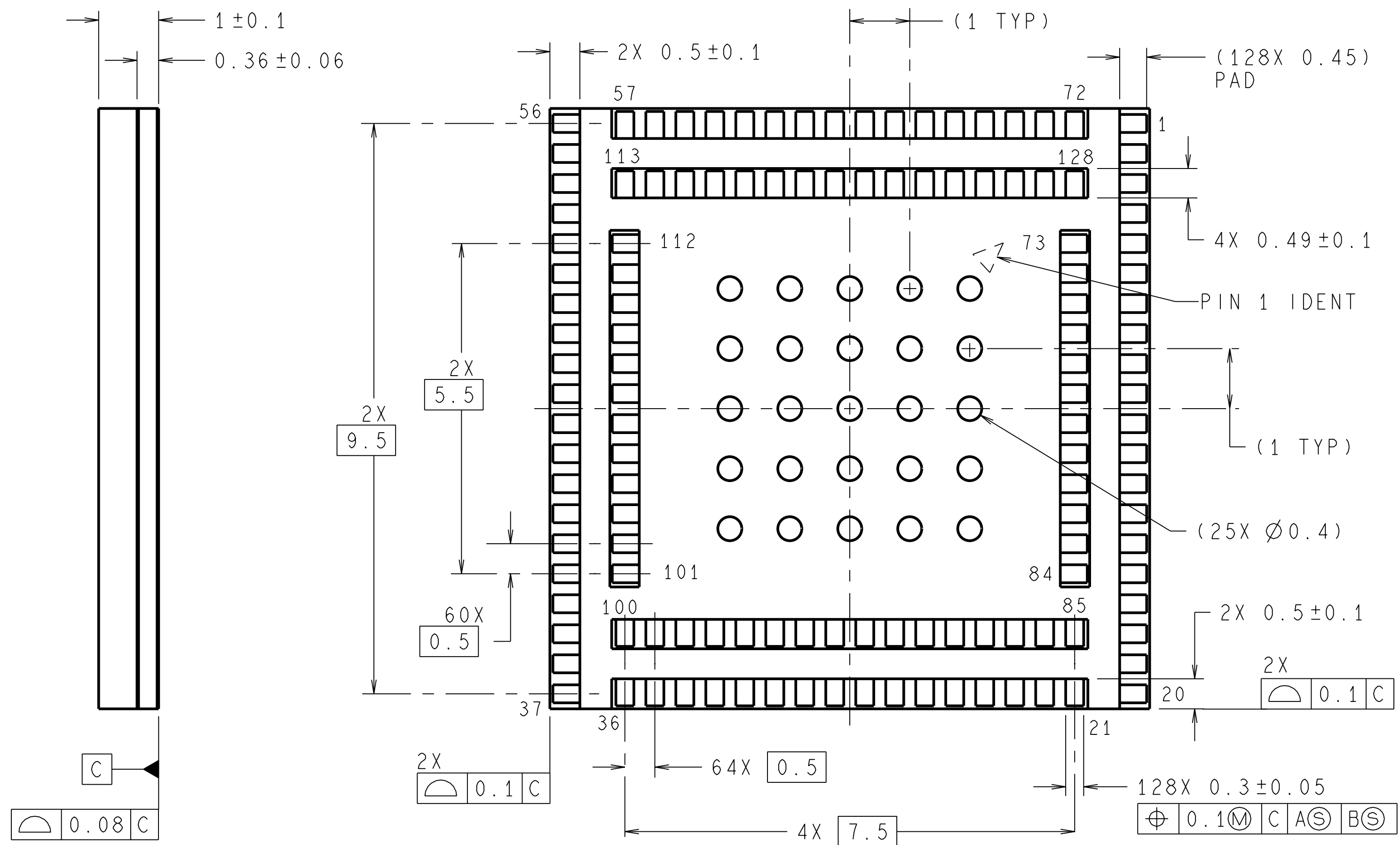
REVISIONS



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS





NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
2. PLATING: Cu 15 TO 20 MICROMETERS
   Ni 10 ± 5 MICROMETERS
   Au 0.75 ± 0.25 MICROMETER
3. REFERENCE JEDEC REGISTRATION MO-208, VARIATION PPEB.

APPROVALS	DATE
DRAWN T. LEQUANG	02/27/2001
DFTG. CHK. MARTA SUCHY	05/25/2001
ENGR. CHK. ANNY TU	05/25/2001

PROJECTION INCH [MM]

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

CSP, PLASTIC, LAMINATED, 10x10x1 mm BODY, 128 L, 0.5 mm PITCH, THERMAL VIAS

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-SLB128B	B

DO NOT SCALE DRAWING — SHEET 1 of 1